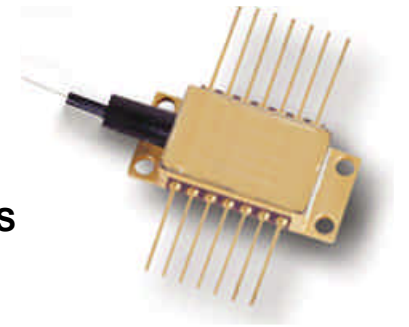


INDIUM & GOLD/TIN SOLDERS FOR PHOTONIC PACKAGING



AIM offers a broad range of solders to fulfill your most challenging component packaging applications. We offer solders for:

- **FIBER TO FERRULE SOLDERING**
- **LASER DIE ATTACH**
- **HERMETIC PACKAGING & SEALING**
- **WETTING & SEALING LASER OPTICS**
- **THERMAL MANAGEMENT**



AIM's full range of specialty joining materials includes indium and gold/tin solders for optoelectronics assembly. When you work with AIM you receive superior products & the technical support you need to produce innovative and reliable packaging solutions. The chart below lists a selection of AIM's most commonly specified solder alloys used in photonic packaging applications. Other alloys are available upon request.

ALLOY COMPOSITION	MELTING RANGE (°C)	TENSILE STRENGTH (ksi)	DENSITY (g/cm ³)	CTE (x10 ⁻⁶ / °C)	CREEP RESISTANCE
80Au/20Sn	280	276	14.5	16	Excellent
88Au/12Ge	356	185	14.7	13	Excellent
96.5Sn/3.5Ag	221	38	7.36	21	High
95Sn/3.5Ag/1.5In	218	51	7.36	22	High
91Sn/9Zn	199	65	7.27	n/a	Good
63Sn/Pb37	183	32	8.40	25	Moderate
62Sn/Pb36/Ag2	179	46	8.41	27	High
CASTIN	217	40	7.30	40	High
LF218	218	40	7.40	40	High
40In/60Pb	195-225	34.5	9.31	26	Moderate
70In/30Pb	160-174	23.8	8.19	28	Moderate
80In/Pb15/Ag5	148-149	17.5	7.85	26	Moderate
100In	156.7	2.5	7.31	29	Poor
97In/3Ag	146	5.5	7.38	22	Poor
52In/48Sn	118	11.9	7.30	24	Low
58Bi/42Sn	138	55	8.56	14	Moderate
40Bi/60Sn	138-170	n/a	8.12	14	Moderate
54Sn/26Pb/20In	138-150	n/a	8.10	25	Moderate
35.7Sn/35.7Pb/28.6Bi	100	24	9.34	20	Low

Whatever your application, AIM has the indium & gold/tin solders and technical support necessary to fulfill your most stringent requirements.

For additional information
please contact AIM at
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1 401 463-5605
1 401 463-0203 Fax
or visit us on the web at
www.aimsolder.com